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Part Number: [0739447016](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 144 Circuits

Documents:
[3D Model](#) [Product Specification PS-73670-9999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73944](#)
Application Backplane
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part Yes
Keying to Mating Part Yes
Material - Metal Phosphor Bronze, Stainless Steel
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.138 In
PC Tail Length (mm) 3.50 mm
PCB Locator Yes
PCB Retention None
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Pitch - Term. Interface (in) 0.079 In
Pitch - Term. Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Polarized to PCB No



Series

image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73944Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
HDM® Backplane Insertion Signal	0621001400
Contact Tool	
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

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NOTES:

1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. SEE SHEET 2 FOR SPECIFIC MATERIAL NUMBERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	A
1	G
SHT	REV

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRWN:MSI BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY	DATE	SALES ASSY HDM BACKPLANE POLAR/GUIDE OPTION SOLDER TAIL VERSION			
			4 PLACES ±---	±---	JB INGHAM	1998/01/14				
			3 PLACES ±---	±---	CHECKED BY	DATE				
			2 PLACES ±0.05	±---	SREED	1998/01/14				
			1 PLACE ±0.10	±---	APPROVED BY	DATE	MOLEX INCORPORATED			
			ANGULAR ±1/2°		CBIXLER	1998/01/14				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
					SEE CHART		SD-73944-001			1 OF 2
					SIZE B		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

LOCATION A



ROW F

ROW A

LOCATION B



LOCATION B

REF. MATERIAL NUMBER 73944-1009
GUIDE PIN IS IN LOCATION A
POLARIZING KEY IS IN LOCATION B, POSITION E

REF. MATERIAL NUMBER 73944-1008
GUIDE PIN IS IN LOCATION B
POLARIZING KEY IS IN LOCATION A, POSITION E

LOCATION A

MATERIAL NUMBER ASSIGNMENT

73944- * * * *

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	31.60	22.00	2.00
1	144	55.60	46.00	2.00
2	72	31.60	22.00	2.50
3	144	55.60	46.00	2.50
4	72	31.60	22.00	3.00
5	144	55.60	46.00	3.00
6	72	31.60	22.00	3.50
7	144	55.60	46.00	3.50

NUMBER	DIM "M"
0	5.00
1	5.50
2	6.00

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	A
01	A	
02	B	
03	A	B
04	B	
05	A	C
06	B	
07	A	D
08	B	
09	A	E
10	B	
11	A	F
12	B	
13	A	G
14	B	
15	A	H
16	B	
17	A	N/A
18	N/A	

SEE SHEET 1
EC No. U81577
DRWN: BINGHAM 98/02/03
CHK: REED 98/02/03
APPR: BIXLER 98/02/03

A

DESCRIPTION
REV

QUALITY SYMBOLS
MAJOR
CRITICAL

GENERAL TOLERANCES:
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.	±.
3 PLACES	±0.	±.
2 PLACES	±0.N/A	±.
1 PLACE	±0.N/A	±.

ANGULAR: ± 1/2°

DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONS

SCALE
2 : 1

DESIGN UNITS
☒ mm ☐ INCH

DRAWN BY & DATE
JBINGHAM 98/01/14
CHECKED BY & DATE
SREED 98/01/14
APPROVED BY & DATE
CBIXLER 98/01/14
CAD FILENAME
S73944X2.DGN

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DIMENSIONS:
☐ mm ☐ INCH ☒ mm ONLY

SHT
REV
REVISE ON
CAD ONLY

TITLE: SALES ASSY, HDM BACKPLANE
POLAR/GUIDE OPTION
SOLDER TAIL VERSION

MOLEX INCORPORATED

MATERIAL NO.
DRAWING NO.
SHEET NO.

SEE CHART
SD-73944-001
2
SIZE
B

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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